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Critical Challenges in Materials Supply to Advanced Semiconductor Manufacturing Fabs

Dr. Anish Tolia, Head of Global Marketing, Linde Electronics May 22, 2015





Key factors in gas supply.



New materials, processes, and adaptable supply chain to meet evolving market needs

Scale Larger fabs and smaller devices mean more gases Quality Changing needs due to complex technology	Supply chain Complex global supply chain management	Sustainability Reduce environmental impact
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Scale. Drivers for increased consumption.



Rapid deployment of very large fabs

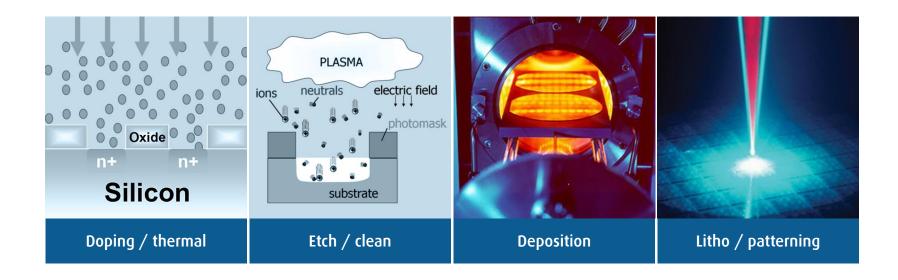
- Typical logic foundry now 80,000 WSPM
- Typical memory fab now exceeding 120,000 WSPM
- Fabs concentrated in clusters (science parks)





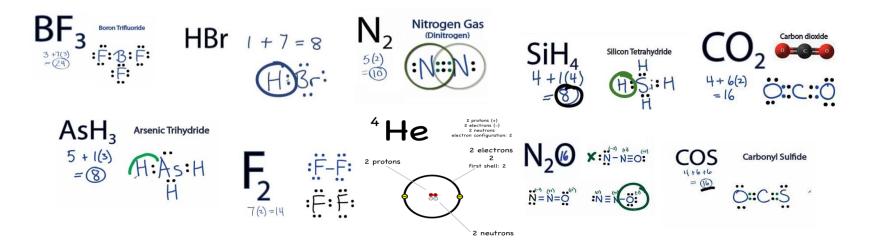


Scale. Several hundred process steps and hundreds of gases and chemicals.





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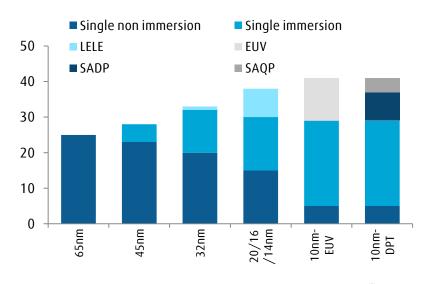
Scale. Drivers for increased consumption.



Multi-patterning

- Move from single-patterning to multi-patterning because of small devices
- Small feature size requiring better optical resolution and move to EUV lithography
- Increased transistor processing (epitaxy, etch, ALD) driving new and increased materials

Number of layers by node



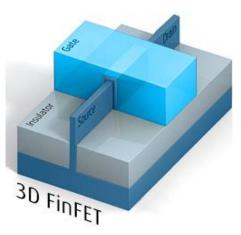


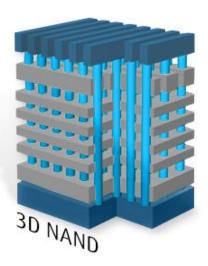
Scale. Drivers for increased consumption.



Move to more complex 3D devices

- 3D FinFET
 - Increased epitaxy steps
 - Increased ALD
- 3D NAND
 - Complex etch
 - Increased deposition



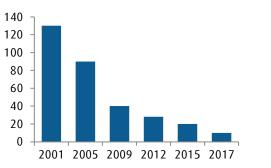


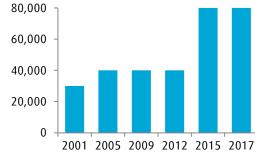


Scale. Increased use of nitrogen.

- Increasing fab capacity drives more consumption
- Advanced technology nodes use more N₂ due to more tools driven by multi-patterning
- Need for on-site generators with increased capacity as gas need increases

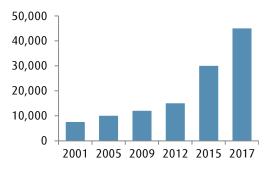
Process node (nm)





Typical fab size (WSPM)

N₂ consumption(Nm³/h)







Scale. Increased use of hydrogen.





Compressed gaseous hydrogen (CGH₂)

Economical transport for short to medium distances



Liquid hydrogen (LH₂)

Economical transport for medium to long distances (only in U.S. and Europe)



On-site production

Production through steam reforming or electrolysis No hydrogen transport costs



Key factors in gas supply.



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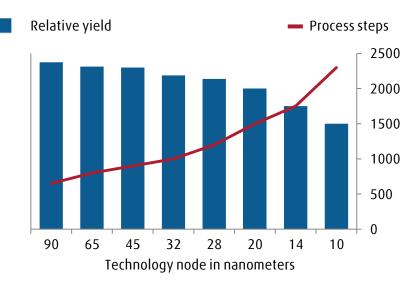
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Quality. Drivers.

- Complexity of processes and reduced yield with each added process
- Risk from higher investments and operational costs
- Engineers not knowing how a specific impurity might impact performance: the challenge of the unknown

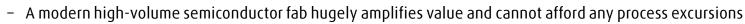
Semi manufacturing yields and steps







Quality. Increasingly important for chip manufacturers at leading technology nodes.



- Stringent focus on controlling variation in all inputs to the chip fabrication process





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Quality. Need for holistic system.

Challenges in meeting demands

- Increase in complexity of monitoring and ensuring process stability across the entire supply chain
- An increasing demand for people such as materials scientists, chemists, and process engineers



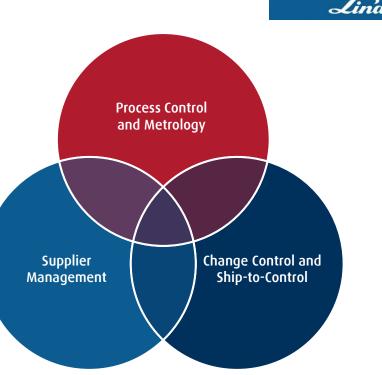




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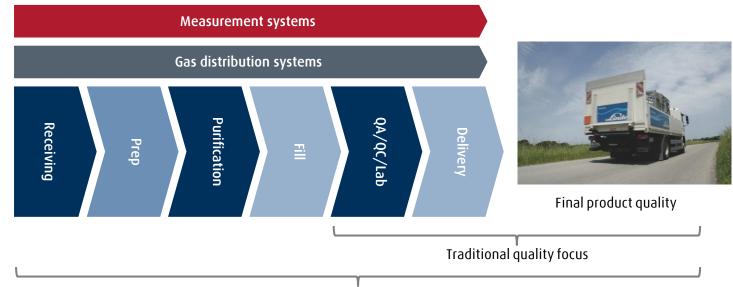






Quality. Need for holistic system.





Measurement systems analysis (MSA), Statistical process/Quality control (SPC/SQC)



Quality. Reduce variability, tighten control limits.



IC technology step changes drive electronic materials purity and analytical requirements

15 to 20 years ago $ ightarrow$	Within the last 10 years $ ightarrow$	Recent / Present $ ightarrow$	Near future
High-purity EMs	High-purity EMs Tight consistency	High-purity EMs Tighter consistency Use of overall process control system	High-purity EMs Tighter consistency Wide use of overall process control system Fingerprinting



Quality. Reduce variability, tighten control limits.

A need for process stability across the entire supply chain

- Rigorous measurement, enabled with fingerprinting and metrology
- Gas purity and consistency/reliability
- Business continuity planning
- Process/statistical quality control







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Supply chain. Global supply chain comes with challenges.

- Capacity planning
 - Usage volumes for specialty gases
 - Visibility into ramp demand of materials for new technologies
- Limited raw materials suppliers
- Security of supply and move to local and regional suppliers
- Natural disasters and shortages
- Transportation labor strikes
- Change in government regulations

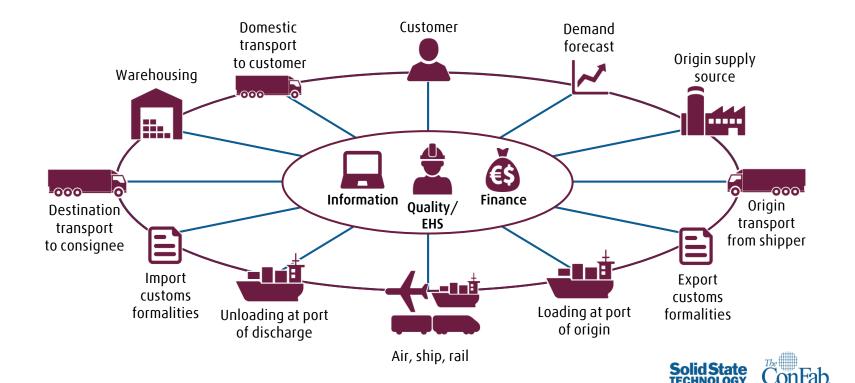


Japan earthquake and tsunami devastation - Source: LA Times



Supply chain. Interlinked, comprehensive, customer-focused.





Supply chain. China and the 2008 Olympics.

- Chinese government block of hazardous materials into multiple ports during the 2008 Olympics
- Materials had to be trucked in and added two months extra delivery time
- Required a lot of advanced planning





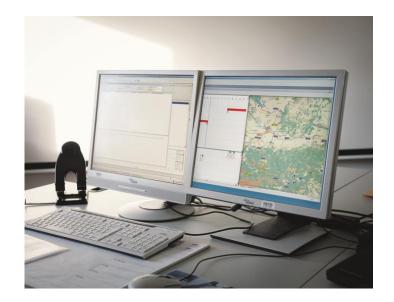




Supply chain. Business Continuity Planning.



- Conduct Business Continuity Planning (BCP) with alert nodes in proactive processes
- Identify potential supply gaps by plotting product-source mapping
- Create raw materials, manufacturing, transportation, and labor shortage contingency plans
- Develop supply gap mitigation and implementation plans





Supply chain. Business Continuity Planning.



- Assess where and how to invest to diversify supply chain on multiple continents
- Do procurement forecasting and planning with customers and suppliers to meet demands
- Acquire two sources for raw materials and have customers qualify both sources
- Establish footprint closer to customer with on-site and local supply plants
- Coach suppliers on Statistical Quality Control (SQC), Statistical
 Process Control (SPC), and customer requirements to show things they do can help customers avert disaster at multiple points in the supply chain





Key factors in gas supply.



New materials, processes, and adaptable supply chain to meet evolving market needs



Sustainability. Big fabs, big use of resources.





Water

10 cubic meters used per wafer at 14 nm node x 80,000 wafers per month x 12 months =

9,600,000 cubic meters of water used per year (enough for 39,506 people in U.S.)



Electricity 1220 kilowatt per hour used per wafer at 14 nm node x 80,000 wafers per month x 12 months = 1,152,000,000 kilowatt – hours or

1,152,000 megawatt – hours electricity used per year (enough for 94,846 people) in U.S.)



Natural gas

61 cubic meters used per wafer at 14 nm node x 80,000 wafers per month x 12 months =

58,560,000 cubic meters of natural gas used per year (enough for 26,899 people in U.S.)



Greenhouse gases

8 greenhouse gases used, which if unabated, are the equivalent of 4.2 tons of CO_2 per wafer. After 90% abatement at 14 nm node x 80,000 wafers per month x 12 months =

400,000 tons CO₂ equivalents used per year



Sustainability. Big fabs, big carbon footprint.



Annual carbon footprint including electricity, natural gas, and chemicals of just one 80,000 wafers per month capacity fab =

1,300,000 tons



Sustainability. Drivers.



- Increasing environmental focus and concerns
- Heightened environmental regulations
- Use of large volumes of rare and high value gases
- Pressure to reduce operating costs



SPECTRA® nitrogen plant (world's best energy efficiency)



Sustainability. Material recovery solutions.



On-site, closed-loop recovery

- Materials recovered on site, purified, and are available for re-use in the manufacturing process

On-site, open-loop recovery

Materials recovered on site and are available for use in other applications

Off-site recovery

- High-cost materials recovered, shipped off site, and purified at an external facility for re-use

Helium recovered on-site and returned to customer

Argon recovered on-site and returned to customer

Xenon recovered and processed off-site

Sulfur hexafluoride recovered on-site and returned to customer

Sulfuric acid recovered on-site and sold to industrial users



Sustainability. Fluorine.



Fluorine technology to reduce emissions by tens of million tons of CO₂ equivalent per year

Global warming potential of greenhouse gases (100 year GWP kg CO₂ eq)

F ₂	NF ₃	SF ₆
0	17,200	22 ,800





Sustainability. Fluorine.



Fluorine technology to reduce emissions by tens of million tons of CO₂ equivalent per year

Case example: Major memory fab

- Using on-site fluorine plants as a safer and more cost-effective alternative to cylinder fluorine for cleaning Chemical Vapor Deposition (CVD) chambers in its manufacturing process
- Using fluorine to replace other fluorinated cleaning gases such as nitrogen trifluoride (NF₃) following tests that demonstrated reductions in cleaning time of up to 40% and a 35% decrease in the mass of gas used





Implications for manufacturers.

Proactively plan up front

Partner with suppliers who

- Commit to your needs
- Value and implement process control and measurement
- Provide security and diversity of supply

Do longer term planning to include

- Building of on-site gas production and recovery
- CAPEX investments







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www.linde-gas.com/electronics electronicsinfo@linde.com

